IXYS

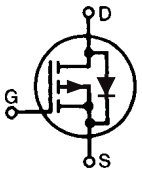
Preliminary Technical Information

PolarP™ Power MOSFET

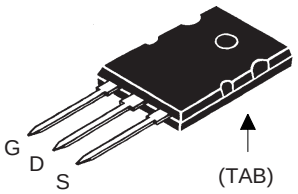
IXTK32P60P
IXTX32P60P

V_{DSS} = - 600V
I_{D25} = - 32A
$R_{DS(on)}$ ≤ 350mΩ

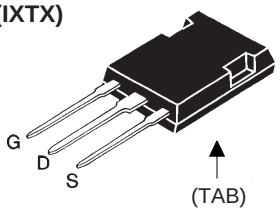
P-Channel Enhancement Mode
Avalanche Rated



TO-264 (IXTK)



PLUS247 (IXTX)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions		Maximum Ratings	
V_{DSS}	T_J = 25°C to 150°C		- 600	V
V_{DGR}	T_J = 25°C to 150°C, R_{GS} = 1MΩ		- 600	V
V_{GSS}	Continuous		±20	V
V_{GSM}	Transient		±30	V
I_{D25}	T_C = 25°C		- 32	A
I_{DM}	T_C = 25°C, pulse width limited by T_{JM}		- 90	A
I_{AR}	T_C = 25°C		- 32	A
E_{AS}	T_C = 25°C		3.5	J
dV/dt	$I_S \le I_{DM}$, $V_{DD} \le V_{DSS}$, $T_J \le 150°C$		10	V/ns
P_D	T_C = 25°C		890	W
T_J			-55 ... +150	°C
T_{JM}			150	°C
T_{stg}			-55 ... +150	°C
T_L	1.6mm (0.062 in.) from case for 10s		300	°C
T_{SOLD}	Plastic body for 10s		260	°C
M_d	Mounting force	(PLUS247)	20..120/4.5..27	N/lb.
	Mounting torque	(TO-264)	1.13/10	Nm/lb.in.
Weight	PLUS247		6	g
	TO-264		10	g

Features

- International standard packages
- Rugged PolarP™ process
- Avalanche Rated
- Low package inductance

Applications

- High side switching
- Push-pull amplifiers
- DC Choppers
- Automatic test equipment

Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
BV_{DSS}	V_{GS} = 0V, I_D = - 250μA	- 600			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = - 250μA	- 2.5		- 4.5	V
I_{GSS}	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
I_{DSS}	$V_{DS} = V_{DSS}$			- 50	μA
	V_{GS} = 0V, T_J = 125°C			- 250	μA
$R_{DS(on)}$	V_{GS} = -10V, $I_D = 0.5 \bullet I_{D25}$, Note 1			350	mΩ

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Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	V_{DS} = -10V, I_D = 0.5 • I_{D25}, Note 1	21	32		S
C_{iss}	V_{GS} = 0V, V_{DS} = - 25V, f = 1MHz		11.1		nF
C_{oss}			925		pF
C_{rss}			77		pF
$t_{d(on)}$	**Resistive Switching Times**		37		ns
t_r	V_{GS} = -10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		27		ns
$t_{d(off)}$	R_G = 1Ω (External)		95		ns
t_f			33		ns
$Q_{g(on)}$	V_{GS} = -10V, V_{DS} = 0.5 • V_{DSS}, I_D = 0.5 • I_{D25}		196		nC
Q_{gs}			54		nC
Q_{gd}			58		nC
R_{thJC}				0.14	°C/W
R_{thCS}			0.15		°C/W

Source-Drain Diode

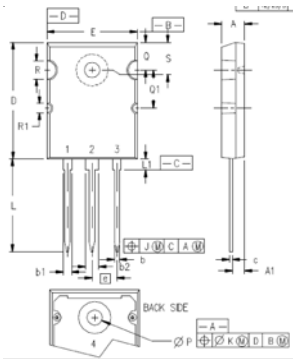
Symbol	Test Conditions (T_J = 25°C, unless otherwise specified)	Characteristic Values Min.	Typ.	Max.	
I_S	V_{GS} = 0V			- 32	A
I_{SM}	Repetitive, pulse width limited by T_{JM}			-128	A
V_{SD}	I_F = -16A, V_{GS} = 0V, Note 1			- 2.8	V
t_{rr}	I_F = -16A, -di/dt = -150A/μs		480		nS
Q_{RM}	V_R = -100V, V_{GS} = 0V		11.4		μC
I_{RM}			- 47.6		A

Note 1: Pulse test, t ≤ 300μs; duty cycle, d ≤ 2%.

PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from data gathered during objective characterizations of preliminary engineering lots; but also may yet contain some information supplied during a pre-production design evaluation. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

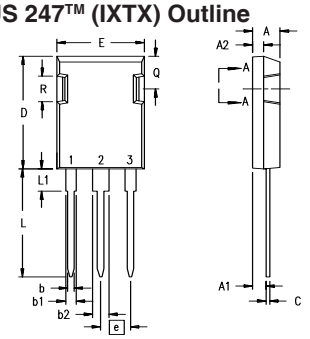
TO-264 (IXTK) Outline



1 – GATE
2, 4 – DRAIN (COLLECTOR)
3 – SOURCE (EMITTER)

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.185	.209	4.70	5.31
A1	.102	.118	2.59	3.00
b	.037	.055	0.94	1.40
b1	.087	.102	2.21	2.59
b2	.110	.126	2.79	3.20
c	.017	.029	0.43	0.74
D	1.007	1.047	25.58	26.59
E	.760	.799	19.30	20.29
e	.215BSC		5.46 BSC	
J	.000	.010	0.00	0.25
K	.000	.010	0.00	0.25
L	.779	.842	19.79	21.39
L1	.087	.102	2.21	2.59
ØP	.122	.138	3.10	3.51
Q	.240	.256	6.10	6.50
Q1	.330	.346	8.38	8.79
ØR	.155	.187	3.94	4.75
ØR1	.085	.093	2.16	2.36
S	.243	.253	6.17	6.43

PLUS 247™ (IXTX) Outline



Terminals: 1 - Gate
2 - Drain (Collector)
3 - Source (Emitter)
4 - Drain (Collector)

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.83	5.21	.190	.205
A_1	2.29	2.54	.090	.100
A_2	1.91	2.16	.075	.085
b	1.14	1.40	.045	.055
b_1	1.91	2.13	.075	.084
b_2	2.92	3.12	.115	.123
C	0.61	0.80	.024	.031
D	20.80	21.34	.819	.840
E	15.75	16.13	.620	.635
e	5.45 BSC		.215 BSC	
L	19.81	20.32	.780	.800
L1	3.81	4.32	.150	.170
Q	5.59	6.20	.220	0.244
R	4.32	4.83	.170	.190

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,850,072 4,881,106 4,931,844 5,017,508 5,034,796 5,049,961 5,063,307 5,187,117 5,237,481 5,381,025 5,486,715 6,162,665 6,259,123 B1 6,306,728 B1 6,404,065 B1 6,534,343 6,583,505 6,683,344 6,710,405 B2 6,710,463 6,727,585 6,759,692 6,771,478 B2 7,005,734 B2 7,063,975 B2 7,071,537 7,157,338B2

Fig. 1. Output Characteristics @ 25ºC

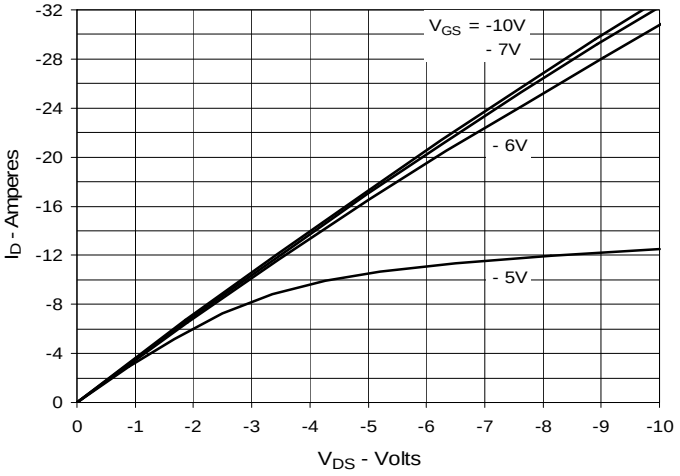


Fig. 2. Extended Output Characteristics @ 25ºC

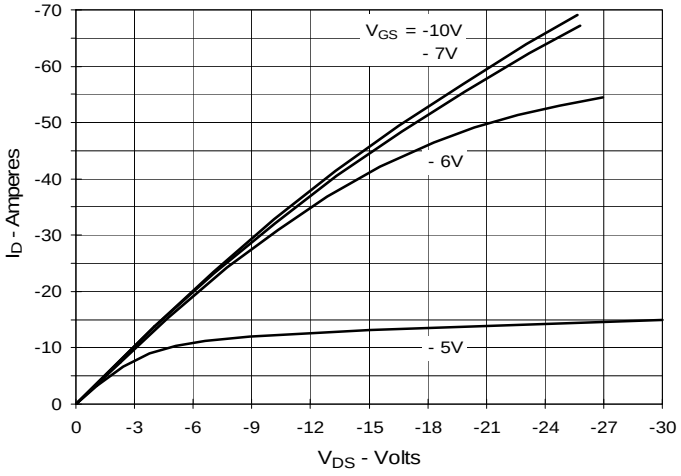


Fig. 3. Output Characteristics @ 125ºC

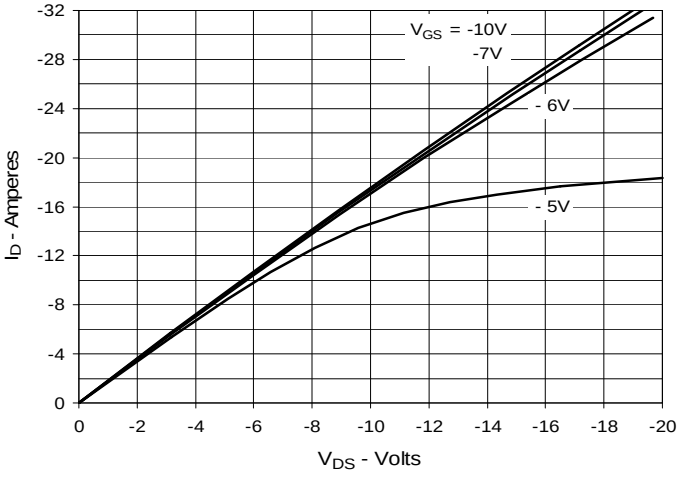


Fig. 4. $R_{DS(on)}$ Normalized to I_D = -16A vs. Junction Temperature

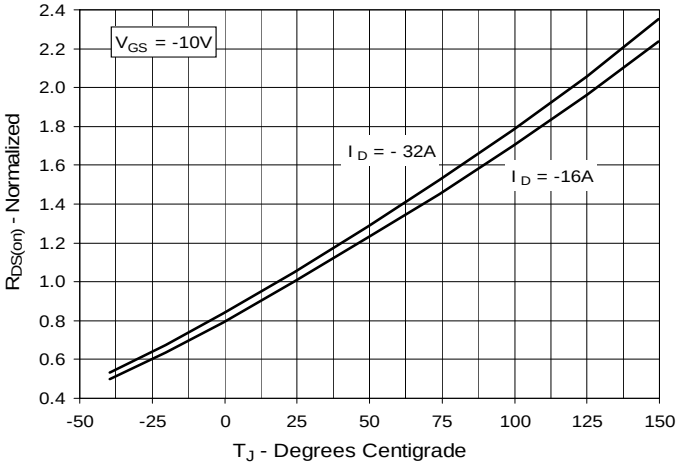


Fig. 5. $R_{DS(on)}$ Normalized to I_D = -16A vs. Drain Current

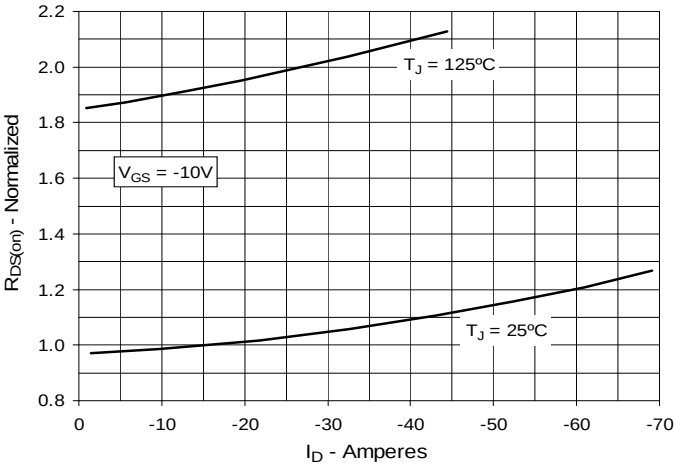


Fig. 6. Maximum Drain Current vs. Case Temperature

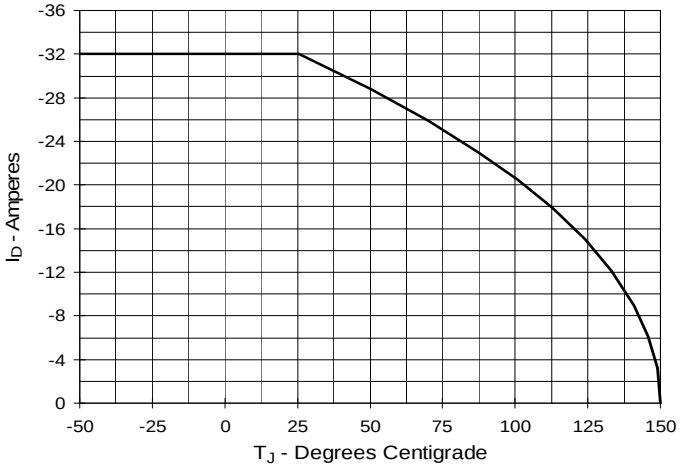


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Fig. 7. Input Admittance

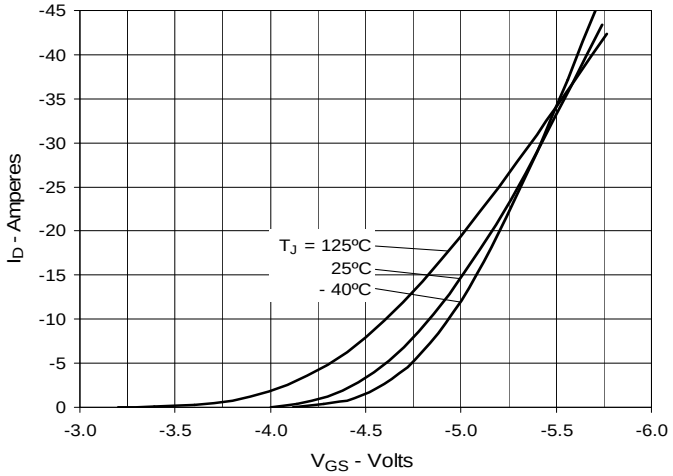

Fig. 8. Transconductance

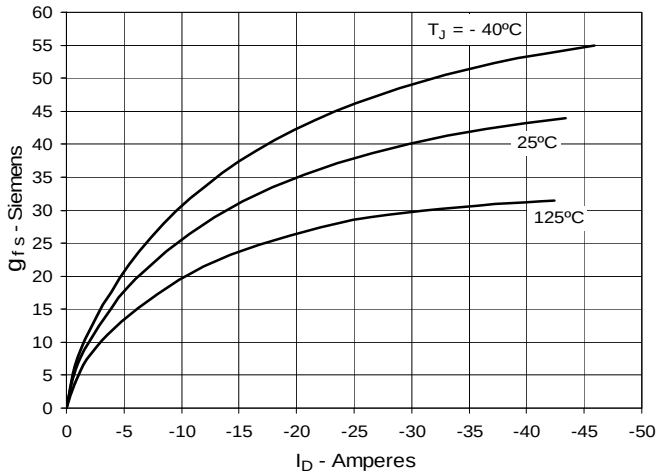

Fig. 9. Forward Voltage Drop of Intrinsic Diode

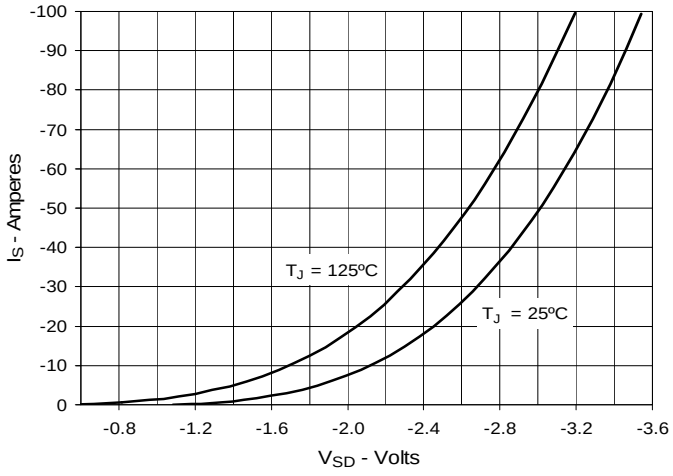

Fig. 10. Gate Charge

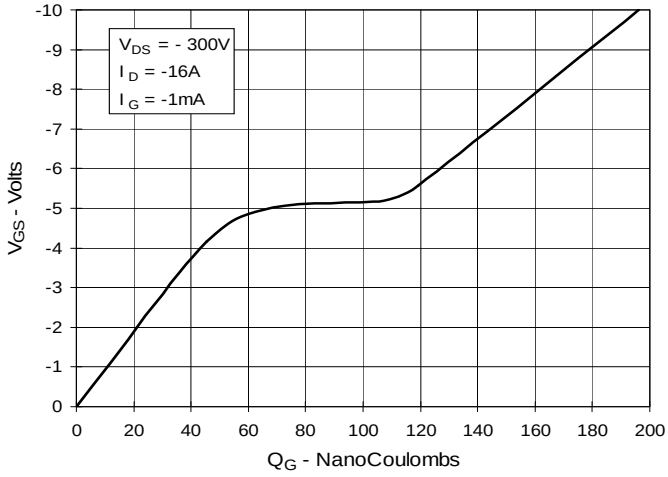

Fig. 11. Capacitance

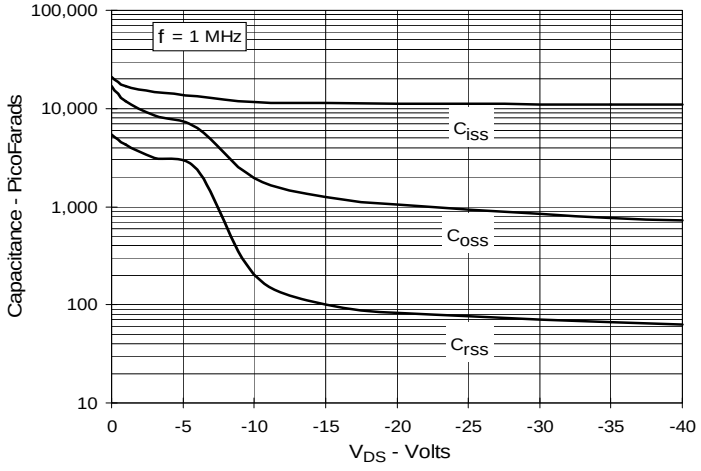

Fig. 12. Forward-Bias Safe Operating Area

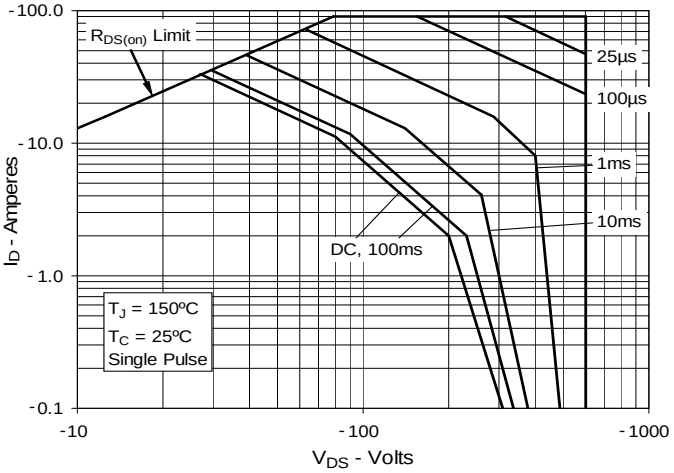

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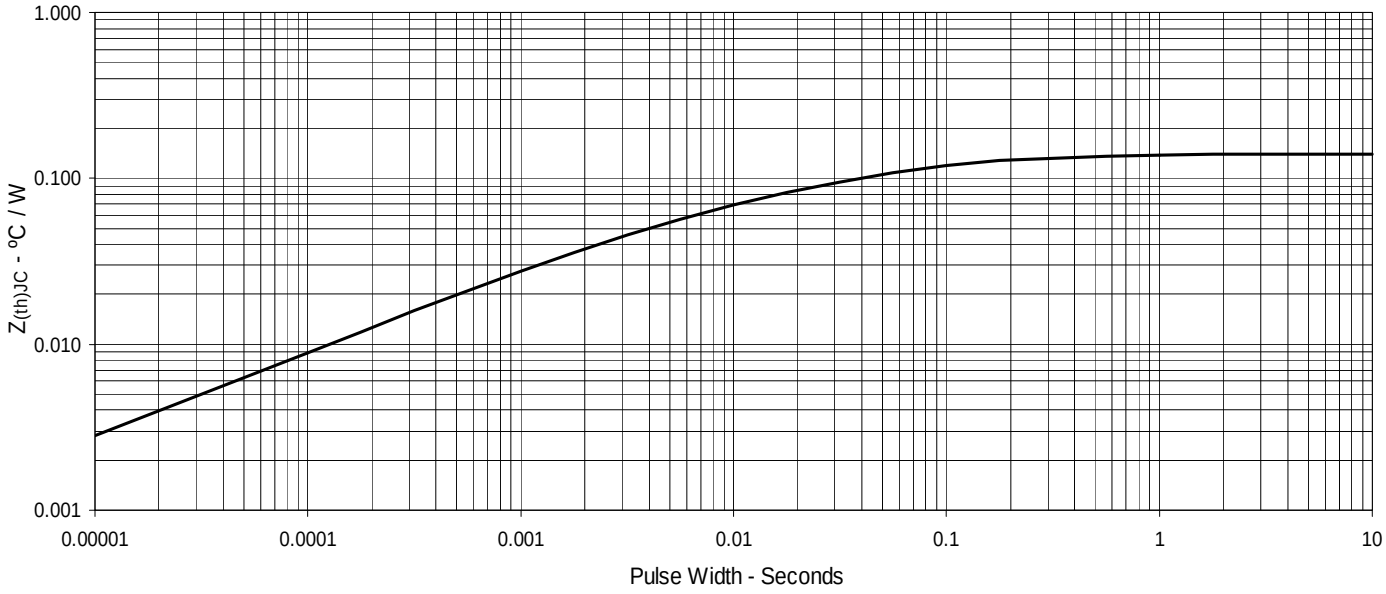
Fig. 13. Maximum Transient Thermal Impedance



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